



Product Change Notification

■ Purpose

[2023-03-22] Sharp Corporation would like to notify customers of an update to a previously announced PCN (Feb. 21, 2022 and Oct. 3, 2022) regarding change of an internal signal processing IC used in the following Sharp distance measuring sensor models:

- GP2Y0A02YK0F
- GP2Y0A21YK0F
- GP2Y0A41SK0F
- GP2Y0A51SK0F
- GP2Y0AF15X
- GP2Y0D02YK0F
- GP2Y0D21YK0F

Originally, Sharp indicated the existing signal processing IC used in these Sharp sensors would be changed to an entirely new IC made by UMC Taiwan. This would have been a major change.

However, the situation has now changed and Sharp will continue using the existing signal processing IC except that the IC will be manufactured by JS Foundry in Japan. This change of IC manufacturer is a much smaller change.

There will be no changes to the Sharp business part number, product shape, pin arrangement, product characteristics or reliability.

■ Effective Time of Change

These are running changes that will be applied starting in February, 2024.

■ Details

Please refer to the pages that follow for more details concerning the changes.

If you have any questions concerning this notification, please contact your Socle representatives at: Socle_Sales_NA@socle-tech.com

SHARP Products Change Notification

Sharp Semiconductor Innovation Corporation

Thank you very much for your continuous usage
of our semiconductor device products.

We would like to inform the change of Distance measuring sensor as follows.



Subject	<u>Notification of the Change in Manufacturing Contractor of DMS Signal Processing IC</u>
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Applicable Product Category	All distance measuring sensor models
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Changed From	Running change is scheduled for February 2024 onward. ※ Depending on the sales situation, the schedule may change.
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We would like to inform our customers of the policy change in regards to the change in manufacturer of DMS signal processing IC.

We have recently made a request for our customers to make a switch to the DMS equipped with signal processing IC manufactured at the UMC factory. This time however, we have made it possible to have our designed and developed in-house IC to be manufactured by JS Foundry, which had bought over the production factory of the current IC.

By mounting this IC, there will be no changes to existing substrates (layout), capacitors, resistors and lead frames.

In addition, we have planned for the signal processing IC to be manufactured on the same production lines and facilities as the current IC, resulting in minimum changes from the current DMS.

Based on the above, we would like to inform you that JS Foundry will be the manufacturing contractor for signal processing IC, and that we will continue to produce the DMS.

We would like to sincerely apologize to our customers for your time spent on evaluating the switch to UMC products. We apologize for the change in policy, but we greatly appreciate your cooperation in continuing to adopt our products.

1. Applicable to all DMS models
2. Content of change

Change in manufacturing factory	
(Manufacturing contractor in previous notice)	UMC, Taiwan
(Manufacturing contractor after change)	JS Foundry Niigata, Japan
3. Reason for change: For continuous supply of DMS

There is no change in the external part number, product shape, pin arrangement, product characteristics and reliability.

測距用信号処理IC変更 対象機種/Applicable distance measuring sensors

系列/Series	タイプ/Type	社外品番/ Applicable Model No.	現行 社内品番/ Current Internal Model No.	新 社内品番/ New Internal Model No.
GP2Y系列	アナログ出力 Analog output	GP2Y0A02YK0F GP2Y0A21YK1F GP2Y0A21YK0F GP2Y0A51SK0F GP2Y0A41SK0F GP2Y0A02YK1F	GP2Y0A02YKF4 GP2Y0A21YK16 GP2Y0A21YKF4 GP2Y0A51SK04 GP2Y0A41SKF4 GP2Y0A02YK14	GP2Y0A02YKFB GP2Y0A21YK1B GP2Y0A21YKFB GP2Y0A51SK0B GP2Y0A41SKFB GP2Y0A02YK1B
	デジタル出力 Digital output (1bit)	GP2Y0D02YK0F GP2Y0D21YK0F GP2Y0D417KBF	GP2Y0D02YKF4 GP2Y0D21YKF4 GP2Y0D417KB4	GP2Y0D02YKFB GP2Y0D21YKFB GP2Y0D417KBB
GP3Y系列	デジタル出力 Digital output (1bit)	GP3Y0D013K GP3Y0D026K0F GP3Y0D026KAF GP3Y0D031K0F GP3Y0D032K0F GP3Y0D033K0F GP3Y0D418K0F	GP3Y0D013K26 GP3Y0D026K06 GP3Y0D026KA6 GP3Y0D031K06 GP3Y0D032K06 GP3Y0D033K06 GP3Y0D418K04	GP3Y0D013K2B GP3Y0D026K0B GP3Y0D026KAB GP3Y0D031K0B GP3Y0D032K0B GP3Y0D033K0B GP3Y0D418K0B
GP2Y0AF系列 /Series (小型測距 /Small type)	アナログ出力 Analog output	GP2Y0AF15R GP2Y0AF15X GP2Y0AF15XR GP2Y0AF15Q GP2Y0AF15Y GP2Y0AF15Y GP2Y0AF30Q GP2Y0AF30R GP2Y0AF30S GP2Y0AF30Y	GP2Y0AF15R04 GP2Y0AF15X04 GP2Y0AF15XR4 GP2Y0AF15Q04 GP2Y0AF15Y04 GP2Y0AF15YS4 GP2Y0AF30Q04 GP2Y0AF30R04 GP2Y0AF30S04 GP2Y0AF30Y04	GP2Y0AF15R0B GP2Y0AF15X0B GP2Y0AF15XRB GP2Y0AF15Q0B GP2Y0AF15Y0B GP2Y0AF15YSB GP2Y0AF30Q0B GP2Y0AF30R0B GP2Y0AF30S0B GP2Y0AF30Y0B

SHARP測距センサ 信号処理IC変更に関する比較表

Comparison sheet related on material change for SHARP Distance sensor

【適応機種/Applicable Model】 測距センサ全モデル/All models

シャープセミコンダクターイノベーション株式会社
Sharp Semiconductor Innovation Corporation

		前回変更後/After 1st Change	今回変更後/After 2nd Change	現行/Before Change	
社外品番/Applicable Model No.		全機種/All models (Same)			
Country of Origin / Manufacturing Location		中国/珠海綠成電子 China / Zhuhai Ensei Electronics Co., Ltd. (Same)			
材料/ Materials	信号処理IC /Signal processing IC	1) IC仕様/IC Spec. 2) Wafer製造工場 /Wafer Factory	端子配置・機能変更有り /Pin assign・Function changed	現行と同一/Same	←
	3)-①基板/Board	ICに合わせた配線パターン変更 /Layout pattern changed to fit new IC (詳細は別添資料参照)	UMC,Taiwan	JS FOUNDRY, Japan	Current factory, Japan
	3)-②抵抗/Resistor	ICに合わせた定数変更・使用数変更 /Constant value and use number changed to fit new IC (詳細は別添資料参照)	ICに合わせた定数変更・使用数変更 /Constant value and use number changed to fit new IC (詳細は別添資料参照)	現行と同一/Same	←
	3)-③コンデンサ/Capacitor	ICに合わせた定数変更・使用数変更 /Constant value and use number changed to fit new IC (詳細は別添資料参照)	ICに合わせた定数変更・使用数変更 /Constant value and use number changed to fit new IC (詳細は別添資料参照)	現行と同一/Same	←
	3)-④リードフレーム/Lead frame	ICに合わせたフレーム変更 / Frame changed to fit new IC (一部機種のみ / Only some models)	ICに合わせたフレーム変更 / Frame changed to fit new IC (一部機種のみ / Only some models)	現行と同一/Same	←
	断面図/Cross section (参考/Reference)				
	その他部材(LED, PSD, Lens付きモールドケース等) /The other materials(LED, PSD, Lens mold case, etc.)	現行と同一/Same			
	電気的特性 / Electronic spec. (絶対最大定格含む/ Including absolute maximum rating.)	現行と同一/Same			
	QC工程 / QC process	現行と同一/Same			
	製品信頼性 / Product Reliability	現行と同一/Same			
外形図/ Outline Dimension	現行と同一/Same				
マーク/ Marking				Stamp	Stamp
梱包仕様 / Package spec	現行と同一/Same				